

74AHC2G32-Q100; 74AHCT2G32-Q100

Dual 2-input OR gate

Rev. 2 — 1 December 2015

Product data sheet

1. General description

The 74AHC2G32-Q100; 74AHCT2G32-Q100 are high-speed Si-gate CMOS devices. They provide two 2-input OR gates.

The AHC device has CMOS input switching levels and supply voltage range 2 V to 5.5 V.

The AHCT device has TTL input switching levels and supply voltage range 4.5 V to 5.5 V.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - ◆ Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$
- Symmetrical output impedance
- High noise immunity
- Low power dissipation
- Balanced propagation delays
- Multiple package options
- ESD protection:
 - ◆ MIL-STD-883, method 3015 exceeds 2000 V
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V ($C = 200\text{ pF}$, $R = 0\text{ }\Omega$)

3. Ordering information

Table 1. Ordering information

| Type number | Package | | | |
|-------------------|---|--------|---|----------|
| | Temperature range | Name | Description | Version |
| 74AHC2G32DP-Q100 | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | TSSOP8 | plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm | SOT505-2 |
| 74AHCT2G32DP-Q100 | | | | |
| 74AHC2G32DC-Q100 | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | VSSOP8 | plastic very thin shrink small outline package; 8 leads; body width 2.3 mm | SOT765-1 |
| 74AHCT2G32DC-Q100 | | | | |
| 74AHC2G32GD-Q100 | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | XSON8 | plastic extremely thin small outline package; no leads; 8 terminals; body $3 \times 2 \times 0.5\text{ mm}$ | SOT996-2 |
| 74AHCT2G32GD-Q100 | | | | |



4. Marking

Table 2. Marking

| Type number | Marking code ^[1] |
|-------------------|-----------------------------|
| 74AHC2G32DP-Q100 | A32 |
| 74AHCT2G32DP-Q100 | C32 |
| 74AHC2G32DC-Q100 | A32 |
| 74AHCT2G32DC-Q100 | C32 |
| 74AHC2G32GD-Q100 | A32 |
| 74AHCT2G32GD-Q100 | C32 |

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram

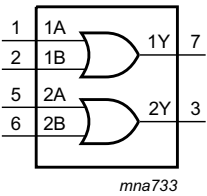


Fig 1. Logic symbol

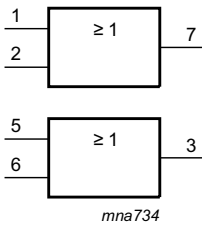


Fig 2. IEC logic symbol

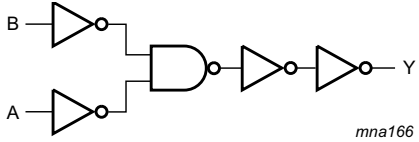


Fig 3. Logic diagram (one gate)

6. Pinning information

6.1 Pinning

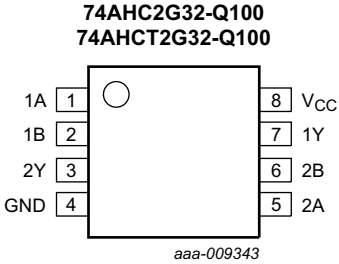


Fig 4. Pin configuration SOT505-2 (TSSOP8) and SOT765-1 (VSSOP8)

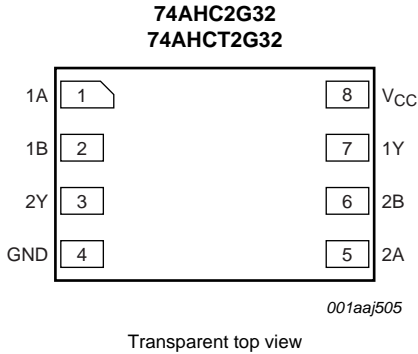


Fig 5. Pin configuration SOT996-2 (XSON8)

6.2 Pin description

Table 3. Pin description

| Symbol | Pin | Description |
|-----------------|------|----------------|
| 1A, 2A | 1, 5 | data input |
| 1B, 2B | 2, 6 | data input |
| GND | 4 | ground (0 V) |
| 1Y, 2Y | 7, 3 | data output |
| V _{CC} | 8 | supply voltage |

7. Functional description

Table 4. Function table^[1]

| Input | | Output |
|-------|----|--------|
| nA | nB | nY |
| L | L | L |
| L | H | H |
| H | L | H |
| H | H | H |

[1] H = HIGH voltage level; L = LOW voltage level.

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|------------------|-------------------------|--|------|------|------|
| V _{CC} | supply voltage | | -0.5 | +7.0 | V |
| V _I | input voltage | | -0.5 | +7.0 | V |
| I _{IK} | input clamping current | V _I < -0.5 V ^[1] | -20 | - | mA |
| I _{OK} | output clamping current | V _O < -0.5 V or V _O > V _{CC} + 0.5 V ^[1] | - | ±20 | mA |
| I _O | output current | -0.5 V < V _O < V _{CC} + 0.5 V | - | ±25 | mA |
| I _{CC} | supply current | | - | 75 | mA |
| I _{GND} | ground current | | -75 | - | mA |
| T _{stg} | storage temperature | | -65 | +150 | °C |
| P _{tot} | total power dissipation | T _{amb} = -40 °C to +125 °C ^[2] | - | 250 | mW |

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For TSSOP8 package: above 55 °C the value of P_{tot} derates linearly with 2.5 mW/K.

For VSSOP8 package: above 110 °C the value of P_{tot} derates linearly with 8 mW/K.

For XSON8 package: above 45 °C the value of P_{tot} derates linearly with 2.4 mW/K.

9. Recommended operating conditions

Table 6. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 74AHC2G32-Q100 | | | 74AHCT2G32-Q100 | | | Unit |
|------------------|-------------------------------------|---------------------------------|----------------|-----|-----------------|-----------------|-----|-----------------|------|
| | | | Min | Typ | Max | Min | Typ | Max | |
| V _{CC} | supply voltage | | 2.0 | 5.0 | 5.5 | 4.5 | 5.0 | 5.5 | V |
| V _I | input voltage | | 0 | - | 5.5 | 0 | - | 5.5 | V |
| V _O | output voltage | | 0 | - | V _{CC} | 0 | - | V _{CC} | V |
| T _{amb} | ambient temperature | | -40 | +25 | +125 | -40 | +25 | +125 | °C |
| Δt/ΔV | input transition rise and fall rate | V _{CC} = 3.3 V ± 0.3 V | - | - | 100 | - | - | - | ns/V |
| | | V _{CC} = 5.0 V ± 0.5 V | - | - | 20 | - | - | 20 | ns/V |

10. Static characteristics

Table 7. Static characteristics

Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|-----------------------|---------------------------|---|-------|-----|------|------------------|------|-------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| 74AHC2G32-Q100 | | | | | | | | | | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 2.0 V | 1.5 | - | - | 1.5 | - | 1.5 | - | V |
| | | V _{CC} = 3.0 V | 2.1 | - | - | 2.1 | - | 2.1 | - | V |
| | | V _{CC} = 5.5 V | 3.85 | - | - | 3.85 | - | 3.85 | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 2.0 V | - | - | 0.5 | - | 0.5 | - | 0.5 | V |
| | | V _{CC} = 3.0 V | - | - | 0.9 | - | 0.9 | - | 0.9 | V |
| | | V _{CC} = 5.5 V | - | - | 1.65 | - | 1.65 | - | 1.65 | V |
| V _{OH} | HIGH-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | | | |
| | | I _O = -50 μA; V _{CC} = 2.0 V | 1.9 | 2.0 | - | 1.9 | - | 1.9 | - | V |
| | | I _O = -50 μA; V _{CC} = 3.0 V | 2.9 | 3.0 | - | 2.9 | - | 2.9 | - | V |
| | | I _O = -50 μA; V _{CC} = 4.5 V | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | I _O = -4.0 mA; V _{CC} = 3.0 V | 2.58 | - | - | 2.48 | - | 2.40 | - | V |
| | | I _O = -8.0 mA; V _{CC} = 4.5 V | 3.94 | - | - | 3.8 | - | 3.70 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | | | |
| | | I _O = 50 μA; V _{CC} = 2.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 50 μA; V _{CC} = 3.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 50 μA; V _{CC} = 4.5 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 4.0 mA; V _{CC} = 3.0 V | - | - | 0.36 | - | 0.44 | - | 0.55 | V |
| | | I _O = 8.0 mA; V _{CC} = 4.5 V | - | - | 0.36 | - | 0.44 | - | 0.55 | V |
| I _I | input leakage current | V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V | - | - | 0.1 | - | 1.0 | - | 2.0 | μA |
| I _{CC} | supply current | V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V | - | - | 1.0 | - | 10 | - | 40 | μA |
| C _I | input capacitance | | - | 1.5 | 10 | - | 10 | - | 10 | pF |

Table 7. Static characteristics ...continued
 Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|------------------------|---------------------------|--|-------|-----|------|------------------|------|-------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| 74AHCT2G32-Q100 | | | | | | | | | | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 4.5 V to 5.5 V | 2.0 | - | - | 2.0 | - | 2.0 | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 4.5 V to 5.5 V | - | - | 0.8 | - | 0.8 | - | 0.8 | V |
| V _{OH} | HIGH-level output voltage | V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V | | | | | | | | |
| | | I _O = -50 µA | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | I _O = -8.0 mA | 3.94 | - | - | 3.8 | - | 3.70 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V | | | | | | | | |
| | | I _O = 50 µA | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 8.0 mA | - | - | 0.36 | - | 0.44 | - | 0.55 | V |
| I _I | input leakage current | V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V | - | - | 0.1 | - | 1.0 | - | 2.0 | µA |
| I _{CC} | supply current | V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V | - | - | 1.0 | - | 10 | - | 40 | µA |
| ΔI _{CC} | additional supply current | per input pin; V _I = 3.4 V; other inputs at V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V | - | - | 1.35 | - | 1.5 | - | 1.5 | mA |
| C _I | input capacitance | | - | 1.5 | 10 | - | 10 | - | 10 | pF |

11. Dynamic characteristics

Table 8. Dynamic characteristics
 GND = 0 V; for test circuit see [Figure 7](#).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|-----------------------|-------------------------------|---|-------|-----|------|------------------|------|-------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| 74AHC2G32-Q100 | | | | | | | | | | |
| t _{pd} | propagation delay | nA, nB to nY; see Figure 6 [1] | | | | | | | | |
| | | V _{CC} = 3.0 V to 3.6 V [2] | | | | | | | | |
| | | C _L = 15 pF | - | 4.4 | 7.9 | 1.0 | 9.5 | 1.0 | 10.0 | ns |
| | | C _L = 50 pF | - | 6.3 | 11.4 | 1.0 | 13.0 | 1.0 | 14.5 | ns |
| | | V _{CC} = 4.5 V to 5.5 V [3] | | | | | | | | |
| | | C _L = 50 pF | - | 4.6 | 7.5 | 1.0 | 8.5 | 1.0 | 9.5 | ns |
| C _{PD} | power dissipation capacitance | per buffer; [4] C _L = 50 pF; f _i = 1 MHz; V _I = GND to V _{CC} | - | 16 | - | - | - | - | - | pF |

Table 8. Dynamic characteristics ...continued
 GND = 0 V; for test circuit see [Figure 7](#).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|------------------------|-------------------------------|---|-------|-----|-----|------------------|-----|-------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| 74AHCT2G32-Q100 | | | | | | | | | | |
| t _{pd} | propagation delay | nA, nB to nY; see Figure 6 [1] | | | | | | | | |
| | | V _{CC} = 4.5 V to 5.5 V [3] | | | | | | | | |
| | | C _L = 15 pF | - | 3.3 | 6.9 | 1.0 | 8.0 | 1.0 | 9.0 | ns |
| | | C _L = 50 pF | - | 4.8 | 7.9 | 1.0 | 9.0 | 1.0 | 10.0 | ns |
| C _{PD} | power dissipation capacitance | per buffer; C _L = 50 pF; f _i = 1 MHz; V _I = GND to V _{CC} [4] | - | 17 | - | - | - | - | - | pF |

- [1] t_{pd} is the same as t_{PLH} and t_{PHL}.
- [2] Typical values are measured at V_{CC} = 3.3 V.
- [3] Typical values are measured at V_{CC} = 5.0 V.
- [4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
 f_i = input frequency in MHz;
 f_o = output frequency in MHz;
 C_L = output load capacitance in pF;
 V_{CC} = supply voltage in V;
 N = number of inputs switching;
 $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

12. Waveforms and test circuit

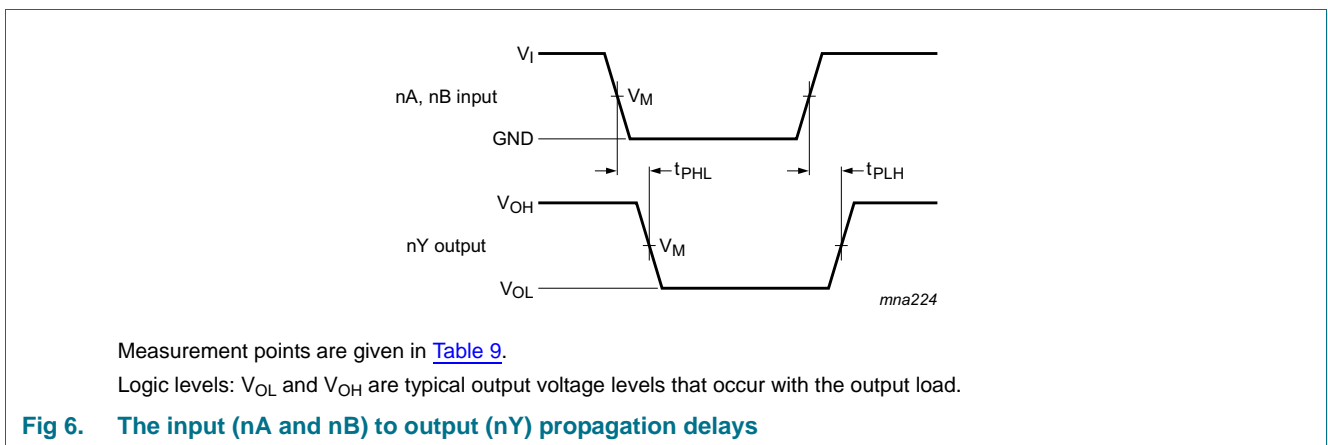
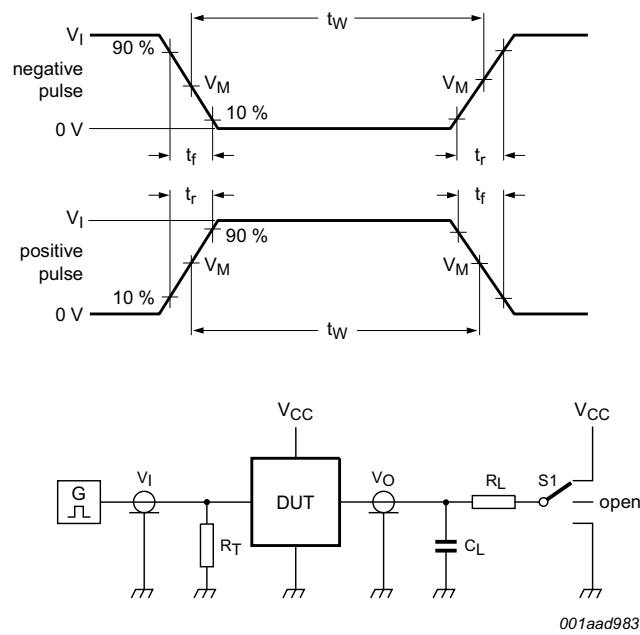


Table 9. Measurement points

| Type | Input | Output |
|-----------------|--------------------|--------------------|
| | V _M | V _M |
| 74AHC2G32-Q100 | 0.5V _{CC} | 0.5V _{CC} |
| 74AHCT2G32-Q100 | 1.5 V | 0.5V _{CC} |



Test data is given in [Table 10](#).

Definitions test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

C_L = Load capacitance including jig and probe capacitance.

R_L = Load resistance.

S1 = Test selection switch.

Fig 7. Test circuit for measuring switching times

Table 10. Test data

| Type | Input | | Load | | S1 position | | |
|-----------------|----------|-------------|--------------|--------------|--------------------|--------------------|--------------------|
| | V_I | t_r, t_f | C_L | R_L | t_{PHL}, t_{PLH} | t_{PZH}, t_{PHZ} | t_{PZL}, t_{PLZ} |
| 74AHC2G32-Q100 | V_{CC} | ≤ 3 ns | 15 pF, 50 pF | 1 k Ω | open | GND | V_{CC} |
| 74AHCT2G32-Q100 | 3 V | ≤ 3 ns | 15 pF, 50 pF | 1 k Ω | open | GND | V_{CC} |

13. Package outline

TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm SOT505-2

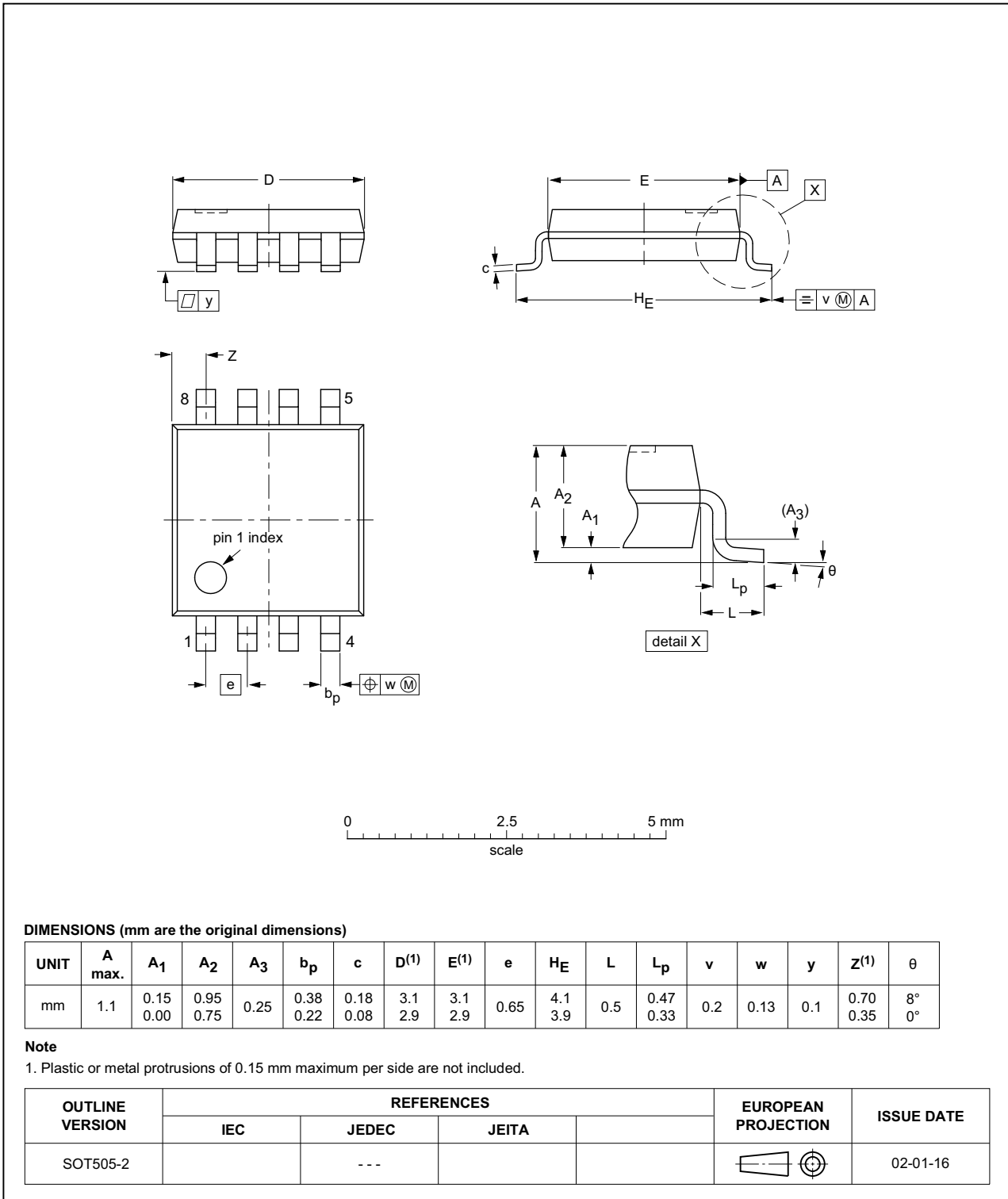


Fig 8. Package outline SOT505-2 (TSSOP8)

VSSOP8: plastic very thin shrink small outline package; 8 leads; body width 2.3 mm

SOT765-1

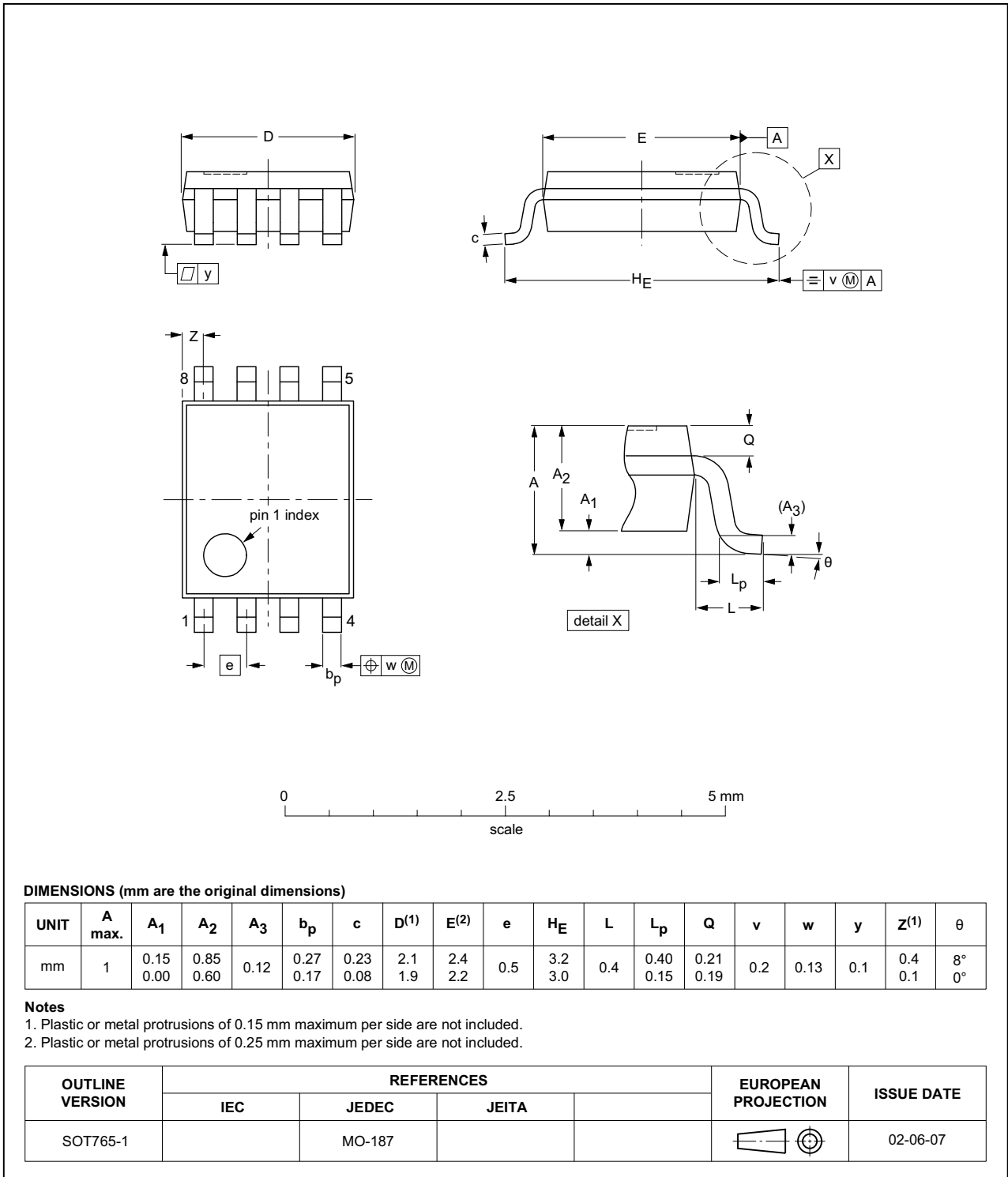


Fig 9. Package outline SOT765-1 (VSSOP8)

XSON8: plastic extremely thin small outline package; no leads;
8 terminals; body 3 x 2 x 0.5 mm

SOT996-2

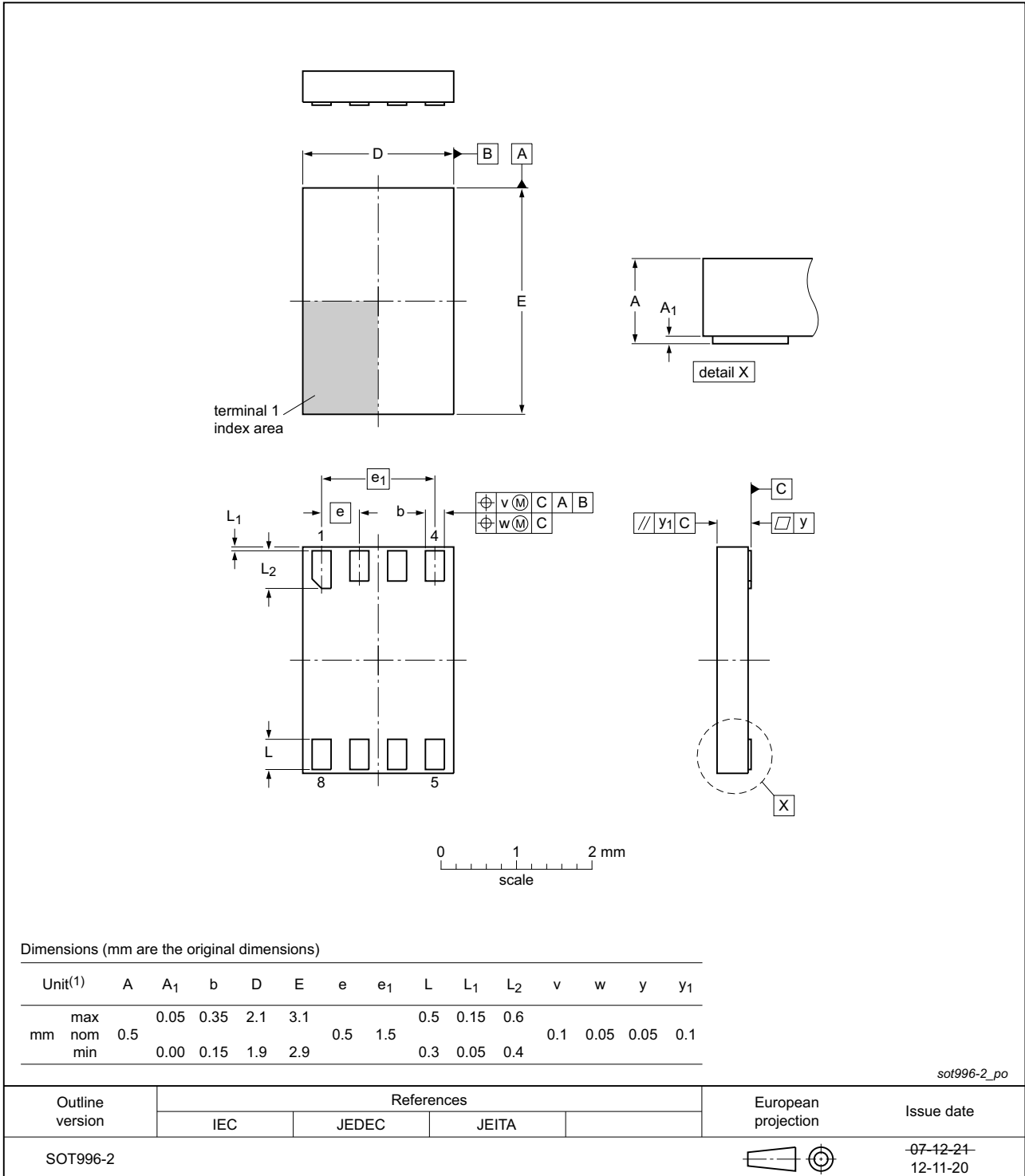


Fig 10. Package outline SOT996-2 (XSON8)

14. Abbreviations

Table 11. Abbreviations

| Acronym | Description |
|---------|---|
| CDM | Charged Device Model |
| CMOS | Complementary Metal-Oxide Semiconductor |
| DUT | Device Under Test |
| ESD | ElectroStatic Discharge |
| HBM | Human Body Model |
| MIL | Military |
| MM | Machine Model |
| TTL | Transistor-Transistor Logic |

15. Revision history

Table 12. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|-------------------------|--|--------------------|---------------|-------------------------|
| 74AHC_AHCT2G32_Q100 v.2 | 20151201 | Product data sheet | - | 74AHC_AHCT2G32_Q100 v.1 |
| Modifications: | <ul style="list-style-type: none"> Added type number 74AHC2G32GD-Q100 and 74AHCT2G32GD-Q100 (SOT996-2/XSON8). | | | |
| 74AHC_AHCT2G32_Q100 v.1 | 20140312 | Product data sheet | - | - |

16. Legal information

16.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
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[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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